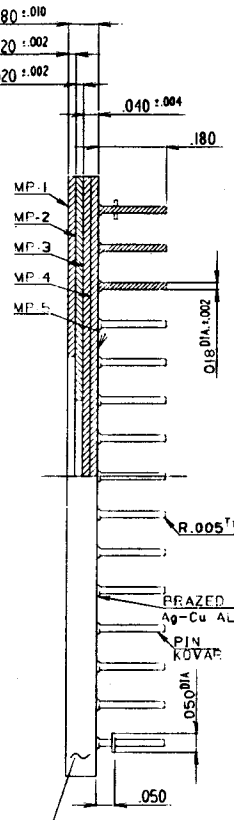


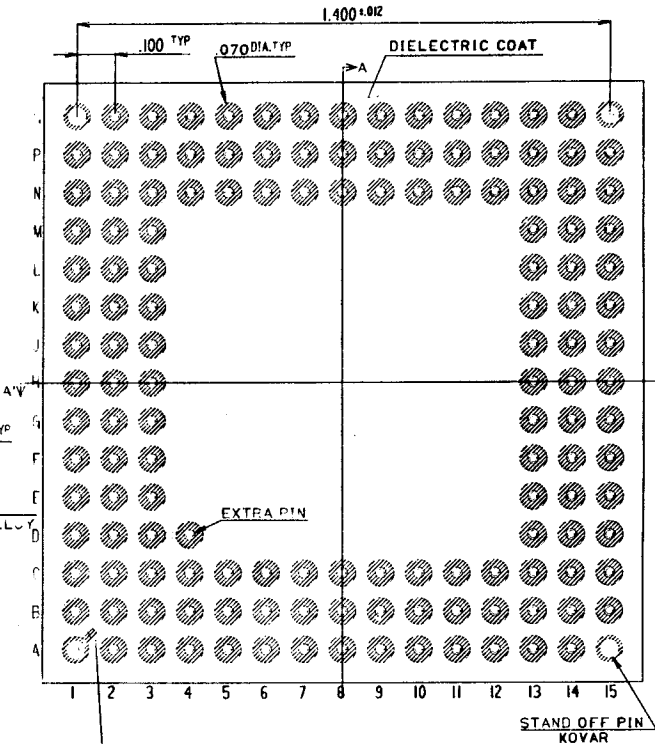
SNAPPING OFF
AFTER Au PLATING

THIS METALLIZED SURFACE TO BE
FLAT WITHIN .003 TIR.

THIS METALLIZED SURFACE TO BE
FLAT WITHIN .002 TIR.



SECTION A-A



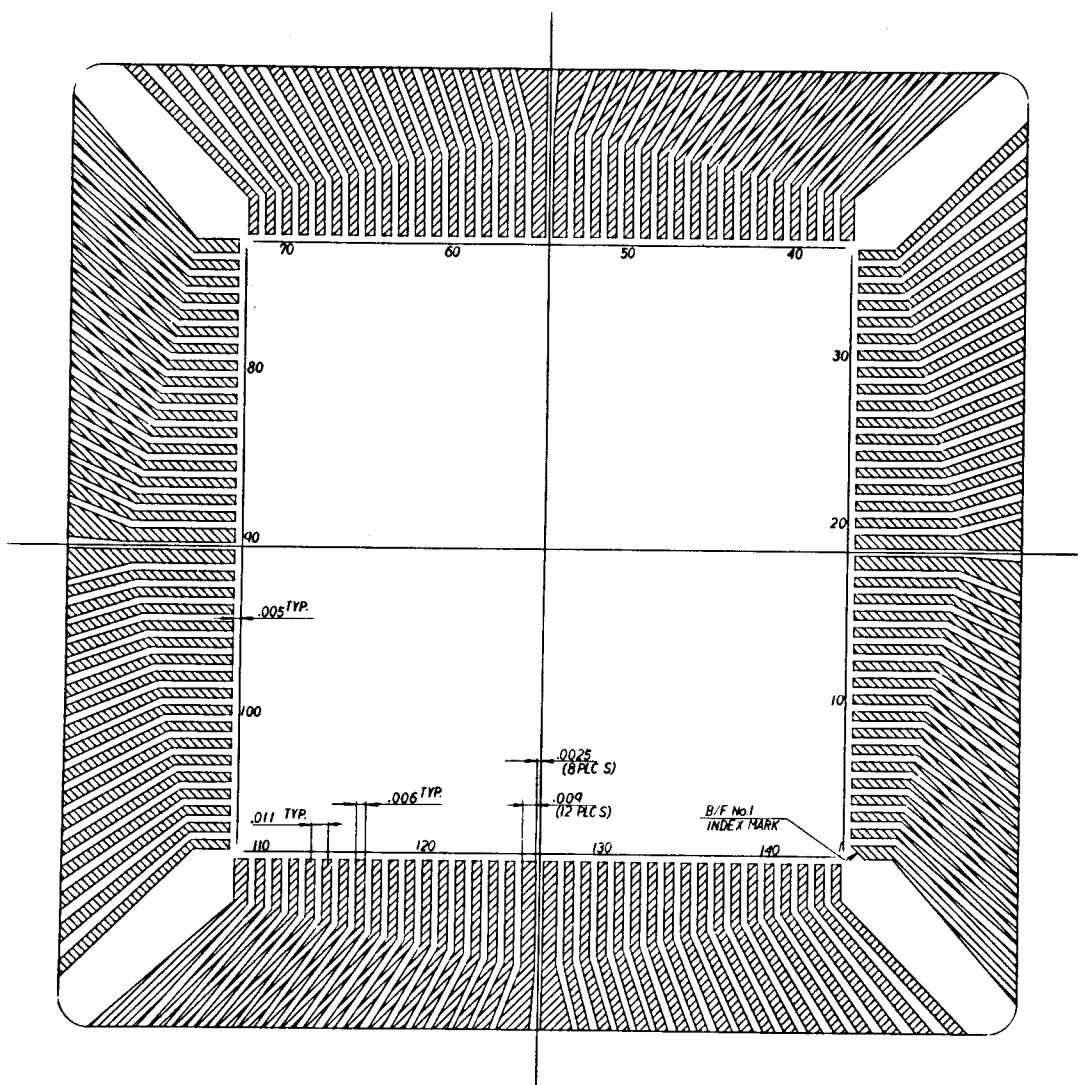
- ACTES.
- 1 PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 - 2 LEAD RESISTANCE
 PIN NO. 18, 19, 54, 55, 40, 41, 126, 127 250 mΩ MAX.
 PIN NO. 1, 37, 73, 104 300 mΩ MAX.
 THE OTHERS 400 mΩ MAX.
 - 3 SEAL AREA TO BE METALLIZED
 - 4 DIE ATTACH AREA TO BE METALLIZED
 - 5 SEAL RING AND DIE ATTACH P/D TO BE FLOATING FROM ANY PINS.

MANUFACTURER'S	NAME	144 PIN GRID ARRAY PACKAGE	TOLERANCES	±10% NLT. ±.005
	SCALE	AS INDICATED	APPROVED	DATE
	DATE	DRAWN	CHECKED	APPROVED

KYOCERA CORPORATION KYOTO JAPAN DWG NO. KD-85032

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PBI44R032-1D-0

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BONDING PATTERN.

MANUFACTURING	NAME	144 PIN GRID ARRAY PACKAGE	TOLERANCES	DRAWN	CHECKED
	SCALE	MATERIAL	UNLESS OTHERWISE SPECIFIED	2/2/85	Totomaru
	20:1			APPROVED	DATE
CHANGE	DATE	DRAWN	CHECKED	APPROVED	
KYOCERA CORPORATION KYOTO JAPAN			DWG NO	KD-85032 1/3	

